

Anthony Luczak

List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/4259176/publications.pdf>

Version: 2024-02-01

10
papers

240
citations

1163117

8
h-index

1474206

9
g-index

10
all docs

10
docs citations

10
times ranked

187
citing authors

#	ARTICLE	IF	CITATIONS
1	Using human factors engineering and Garvin's product quality to develop a basketball shoe taxonomy. Proceedings of the Institution of Mechanical Engineers, Part P: Journal of Sports Engineering and Technology, 2022, 236, 60-69.	0.7	1
2	State-of-the-art review of athletic wearable technology: What 113 strength and conditioning coaches and athletic trainers from the USA said about technology in sports. International Journal of Sports Science and Coaching, 2020, 15, 26-40.	1.4	65
3	Closing the Wearable Gap-Part VII: A Retrospective of Stretch Sensor Tool Kit Development for Benchmark Testing. Electronics (Switzerland), 2020, 9, 1457.	3.1	8
4	Closing the Wearable Gap-Part VI: Human Gait Recognition Using Deep Learning Methodologies. Electronics (Switzerland), 2020, 9, 796.	3.1	19
5	Wearable Stretch Sensors for Human Movement Monitoring and Fall Detection in Ergonomics. International Journal of Environmental Research and Public Health, 2020, 17, 3554.	2.6	56
6	Closing the Wearable Gap-Part V: Development of a Pressure-Sensitive Sock Utilizing Soft Sensors. Sensors, 2020, 20, 208.	3.8	17
7	Closing the Wearable Gap-Part II: Sensor Orientation and Placement for Foot and Ankle Joint Kinematic Measurements. Sensors, 2019, 19, 3509.	3.8	22
8	Closing the Wearable Gap-Part III: Use of Stretch Sensors in Detecting Ankle Joint Kinematics During Unexpected and Expected Slip and Trip Perturbations. Electronics (Switzerland), 2019, 8, 1083.	3.1	18
9	Closing the Wearable Gap-Part IV: 3D Motion Capture Cameras Versus Soft Robotic Sensors Comparison of Gait Movement Assessment. Electronics (Switzerland), 2019, 8, 1382.	3.1	12
10	Closing the Wearable Gap: Mobile Systems for Kinematic Signal Monitoring of the Foot and Ankle. Electronics (Switzerland), 2018, 7, 117.	3.1	22